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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	700MHz
Primary Attributes	FPGA - 462K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxbb5d6f35c6n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Feature		Description					
Embedded Hard IP blocks	Memory controller (Arria V GX, GT, SX, and ST only) Embedded transceiver I/O	 Native support for up to four signal processing precision levels: Three 9 x 9, two 18 x 18, or one 27 x 27 multiplier in the same variable-precision DSP block One 36 x 36 multiplier using two variable-precision DSP blocks (Arria V GZ devices only) 64-bit accumulator and cascade for systolic finite impulse responses (FIRs) Embedded internal coefficient memory Preadder/subtractor for improved efficiency DDR3 and DDR2 Custom implementation: Arria V GX and SX devices—up to 6.5536 Gbps Arria V GT and ST devices—up to 10.3125 Gbps Arria V GZ devices—up to 12.5 Gbps PCI Express® (PCIe®) Gen2 (x1, x2, or x4) and Gen1 (x1, x2, x4, or x8) hard IP with multifunction support, endpoint, and root port PCIe Gen3 (x1, x2, x4, or x8) support (Arria V GZ only) Gbps Ethernet (GbE) and XAUI physical coding sublayer (PCS) Common Public Radio Interface (CPRI) PCS Gigabit-capable passive optical network (GPON) PCS 10-Gbps Ethernet (10GbE) PCS (Arria V GZ only) Serial RapidIO® (SRIO) PCS Interlaken PCS (Arria V GZ only) 					
Clock networks	-	bal clock network nd peripheral clock networks at are not used can be powered down to reduce dynamic power					
Phase-locked loops (PLLs)	Precision clock syn (ZDB)Integer mode and f	gh-resolution fractional PLLs ecision clock synthesis, clock delay compensation, and zero delay buffering DB) teger mode and fractional mode Coscillator ATX transmitter PLLs (Arria V GZ only)					



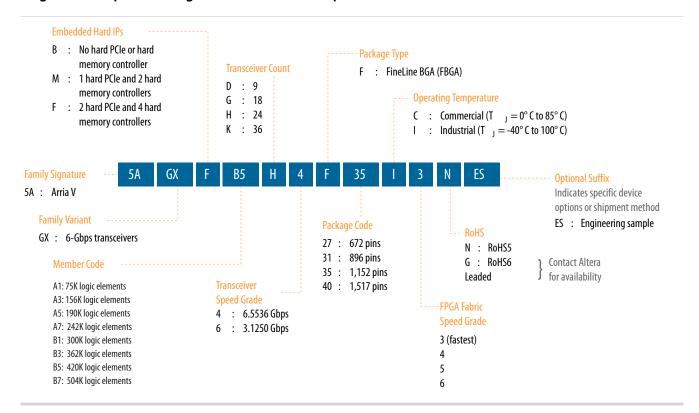
Feature	Description
FPGA General- purpose I/Os (GPIOs)	 1.6 Gbps LVDS receiver and transmitter 800 MHz/1.6 Gbps external memory interface On-chip termination (OCT) 3.3 V support (2)
External Memory Interface	 Memory interfaces with low latency: Hard memory controller-up to 1.066 Gbps Soft memory controller-up to 1.6 Gbps
Low-power high- speed serial interface	 600 Mbps to 12.5 Gbps integrated transceiver speed Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only)
HPS (Arria V SX and ST devices only)	 Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers On-chip RAM and boot ROM HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage



 $^{^{(2)}~{\}rm Arria~V~GZ}$ devices support 3.3 V with a 3.0 V ${\rm V}_{\rm CCIO}.$

Available Options

Figure 1: Sample Ordering Code and Available Options for Arria V GX Devices



Maximum Resources

Table 4: Maximum Resource Counts for Arria V GX Devices

Poso	Resource		Member Code							
neso	urce	A1	А3	A 5	A7	B1	В3	B5	В7	
Logic I (LE) (F	Elements ()	75	156	190	242	300	362	420	504	
ALM		28,302	58,900	71,698	91,680	113,208	136,880	158,491	190,240	
Registe	Register		235,600	286,792	366,720	452,832	547,520	633,964	760,960	
Mem	M10K	8,000	10,510	11,800	13,660	15,100	17,260	20,540	24,140	
ory (Kb)	MLAB	463	961	1,173	1,448	1,852	2,098	2,532	2,906	
	Variable- precision DSP Block		396	600	800	920	1,045	1,092	1,156	
	18 x 18 Multiplier		792	1,200	1,600	1,840	2,090	2,184	2,312	
PLL		10	10	12	12	12	12	16	16	



Resource		Member Code					
Neso	nesource		C 7	D3	D7		
Transceiver	6 Gbps ⁽⁴⁾	3 (9)	6 (24)	6 (24)	6 (36)		
Transcerver	10 Gbps ⁽⁵⁾	4	12	12	20		
GPIO ⁽⁶⁾	GPIO ⁽⁶⁾		544	704	704		
LVDS	Transmitter	68	120	160	160		
LVD3	Receiver	80	136	176	176		
PCIe Hard IP	PCIe Hard IP Block		2	2	2		
Hard Memor	y Controller	2	4	4	4		

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

• Transceiver Architecture in Arria V Devices

Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 7: Package Plan for Arria V GT Devices

Memb	F672 (27 mm)				F1152 (35 mm)			F1517 (40 mm)				
er Code		ХС	VR		ХС	VR	XCVR		XCVR		2	KCVR
	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10-Gbps
C3	336	3 (9)	4	416	3 (9)	4	_	_	_	_	_	_
C7	_	_	_	384	6 (18)	8	544	6 (24)	12	_	_	_
D3	_	_	_	384	6 (18)	8	544	6 (24)	12	704	6 (24)	12
D7	_	_	_	_	_	_	544	6 (24)	12	704	6 (36)	20

The 6-Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10-Gbps channels as three 6-Gbps channels—the total number of 6-Gbps channels are shown in brackets. For example, you can also configure the Arria V GT D7 device in the F1517 package with nine 6-Gbps



⁽⁴⁾ The 6 Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10 Gbps channels as three 6 Gbps channels-the total number of 6 Gbps channels are shown in brackets.

⁽⁵⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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and eighteen 10-Gbps, twelve 6-Gbps and sixteen 10-Gbps, fifteen 6-Gbps and fourteen 10-Gbps, or up to thirty-six 6-Gbps with no 10-Gbps channels.

Arria V GZ

This section provides the available options, maximum resource counts, and package plan for the Arria V GZ devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

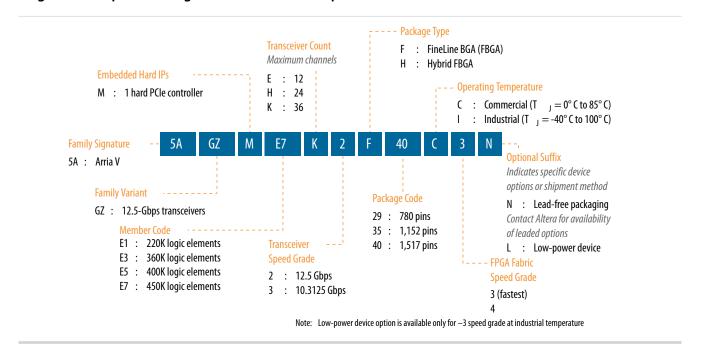
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 3: Sample Ordering Code and Available Options for Arria V GZ Devices



Maximum Resources

Table 8: Maximum Resource Counts for Arria V GZ Devices

Resource	Member Code					
nesource	E1	E 3	E 5	E 7		
Logic Elements (LE) (K)	220	360	400	450		
ALM	83,020	135,840	150,960	169,800		
Register	332,080	543,360	603,840	679,200		



Poss	ource	Member Code			
neso	ruice	В3	B5		
FPGA PLL		14	14		
HPS PLL		3	3		
6 Gbps Transceiver		30	30		
FPGA GPIO ⁽⁸⁾		540	540		
HPS I/O		208	208		
LVDS	Transmitter	120	120		
LVDS	Receiver	136	136		
PCIe Hard IP Block		2	2		
FPGA Hard Memory	Controller	3	3		
HPS Hard Memory C	Controller	1	1		
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core		

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 11: Package Plan for Arria V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

	F896				F1152			F1517		
Member	(31 mm)			(35 mm)			(40 mm)			
Code	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR	
В3	250	208	12	385	208	18	540	208	30	
B5	250	208	12	385	208	18	540	208	30	

Arria V ST

This section provides the available options, maximum resource counts, and package plan for the Arria V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



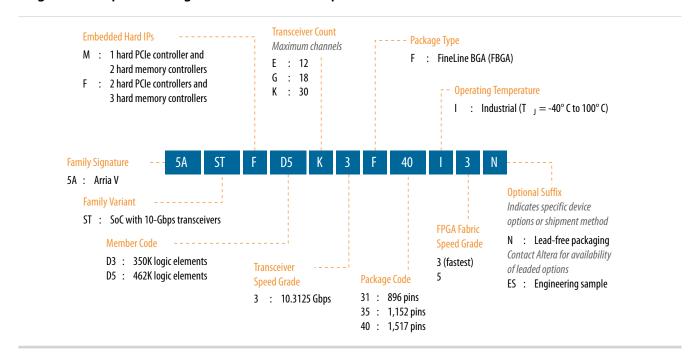
⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

Reso	LINEO	Member Code			
Reso	ource	D3	D5		
Logic Elements (LE)	(K)	350	462		
ALM		132,075	174,340		
Register		528,300	697,360		
Memory (Kb)	M10K	17,290	22,820		
Memory (Rb)	MLAB	2,014	2,658		
Variable-precision D	SP Block	809	1,090		
18 x 18 Multiplier		1,618	2,180		
FPGA PLL		14	14		
HPS PLL		3	3		
Transceiver	6-Gbps	30	30		
Transcerver	10-Gbps ⁽⁹⁾	16	16		



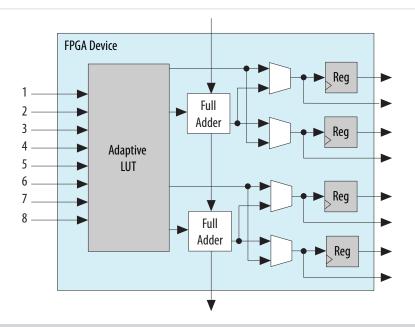
- Managing Device I/O Pins chapter, Quartus Prime Handbook Provides more information about vertical I/O migrations.
- Power Management in Arria V Devices
 Describes the power-up sequence required for Arria V GX and GT devices.

Adaptive Logic Module

Arria V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 7: ALM for Arria V Devices



You can configure up to 50% of the ALMs in the Arria V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Arria V Devices on page 20

Lists the embedded memory capacity for each device.



Variable-Precision DSP Block

Arria V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18, 27 x 27, and 36 x 36 bits natively
- A 64-bit accumulator
- Double accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Dynamic coefficients
- 18-bit internal coefficient register banks
- Enhanced independent multiplier operation
- Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Quartus Prime design software

Table 14: Variable-Precision DSP Block Configurations for Arria V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters	Two 18 x 18 with accumulate	1
Single-precision floating- point implementations	One 27 x 27	1
Very high precision fixed point implementations	One 36 x 36	2

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27×27 multipliers. Using two DSP block resources, you can also configure a 36×36 multiplier for high-precision applications. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.



Table 15: Number of Multipliers in Arria V Devices

The table lists the variable-precision DSP resources by bit precision for each Arria V device.

Variant	Mem ber	Variable- precision	Independ	ent Input and Ope	18 x 18 Multiplier	18 x 18 Multiplier Adder Summed			
Variant	Code	DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	36 x 36 Multiplier	Adder Mode	with 36 bit Input	
	A1	240	720	480	240	_	240	240	
	A3	396	1,188	792	396	_	396	396	
	A5	600	1,800	1,200	600	_	600	600	
Arria V	A7	800	2,400	1,600	800	_	800	800	
GX	B1	920	2,760	1,840	920	_	920	920	
	В3	1,045	3,135	2,090	1,045	_	1,045	1,045	
	B5	1,092	3,276	2,184	1,092	_	1,092	1,092	
	B7	1,156	3,468	2,312	1,156	_	1,156	1,156	
	C3	396	1,188	792	396	_	396	396	
Arria V	C7	800	2,400	1,600	800	_	800	800	
GT	D3	1,045	3,135	2,090	1,045	_	1,045	1,045	
	D7	1,156	3,468	2,312	1,156	_	1,156	1,156	
	E1	800	2,400	1,600	800	400	800	800	
Arria V	Е3	1,044	3,132	2,088	1,044	522	1,044	1,044	
GZ	E5	1,092	3,276	2,184	1,092	546	1,092	1,092	
	E7	1,139	3,417	2,278	1,139	569	1,139	1,139	
Arria V	В3	809	2,427	1,618	809	_	809	809	
SX	B5	1,090	3,270	2,180	1,090	_	1,090	1,090	
Arria V	D3	809	2,427	1,618	809	_	809	809	
ST	D5	1,090	3,270	2,180	1,090	_	1,090	1,090	

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



Types of Embedded Memory

The Arria V devices contain two types of memory blocks:

- 20 Kb M20K or 10 Kb M10K blocks—blocks of dedicated memory resources. The M20K and M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Arria V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB. You can also configure these ALMs, in Arria V GZ devices, as ten 64 x 1 blocks, giving you one 64 x 10 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Arria V Devices

Table 16: Embedded Memory Capacity and Distribution in Arria V Devices

		M20K		M10K		MLAB		
Variant	Membe r Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
	A1	_	_	800	8,000	741	463	8,463
	A3	_	_	1,051	10,510	1538	961	11,471
	A5	_	_	1,180	11,800	1877	1,173	12,973
Arria V GX	A7	_	_	1,366	13,660	2317	1,448	15,108
Allia V GA	B1	_	_	1,510	15,100	2964	1,852	16,952
	В3	_	_	1,726	17,260	3357	2,098	19,358
	B5	_	_	2,054	20,540	4052	2,532	23,072
	В7	_	_	2,414	24,140	4650	2,906	27,046
Arria V GT	C3	_	_	1,051	10,510	1538	961	11,471
	C7	_	_	1,366	13,660	2317	1,448	15,108
	D3	_	_	1,726	17,260	3357	2,098	19,358
	D7	_	_	2,414	24,140	4650	2,906	27,046
Arria V GZ	E1	585	11,700	_	_	4,151	2,594	14,294
	E3	957	19,140	_	_	6,792	4,245	23,385
	E5	1,440	28,800	_	_	7,548	4,718	33,518
	E7	1,700	34,000	_	_	8,490	5,306	39,306
Arria V SX	В3	_	_	1,729	17,290	3223	2,014	19,304
	B5	_	_	2,282	22,820	4253	2,658	25,478



External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

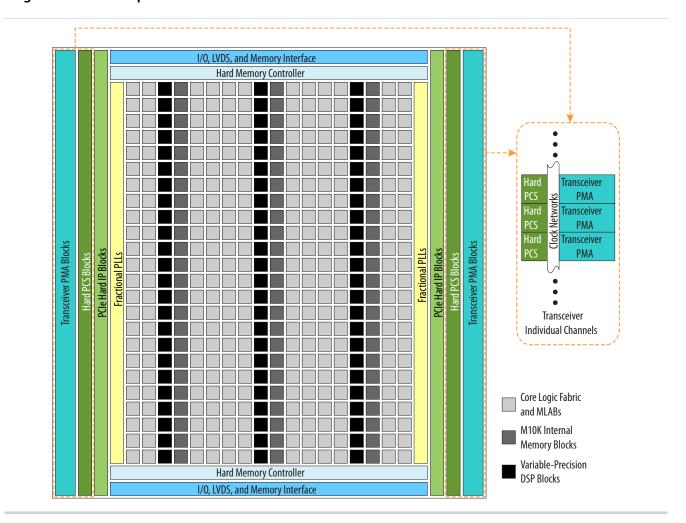
Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.



Figure 9: Device Chip Overview for Arria V GX and GT Devices





PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
PCIe Gen1 (x1, x2, x4, x8) PCIe Gen2 ⁽¹⁴⁾ (x1, x2, x4)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder PIPE 2.0 interface to the core logic 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO PIPE 2.0 interface to the core logic
GbE	1.25	Phase compensation FIFOByte serializer8B/10B encoder	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO
XAUI ⁽¹⁵⁾	3.125	 Phase compensation FIFO Byte serializer 8B/10B encoder XAUI state machine for bonding four channels 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO XAUI state machine for realigning four channels Deskew FIFO circuitry
SDI	0.27 ⁽¹⁶⁾ , 1.485, 2.97	Phase compensation FIFO Byte serializer	Byte deserializerPhase compensation FIFO
GPON ⁽¹⁷⁾	1.25 and 2.5	byte serializer	1 mase compensation in O
CPRI ⁽¹⁸⁾	0.6144 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder TX deterministic latency 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO RX deterministic latency



⁽¹³⁾ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCIe Gen2 is supported only through the PCIe hard IP.

⁽¹⁵⁾ XAUI is supported through the soft PCS.

⁽¹⁶⁾ The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

 $^{^{\}left(17\right) }$ The GPON standard does not support burst mode.

⁽¹⁸⁾ CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

Table 22: Transceiver PCS Features for Arria V GZ Devices

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
Custom PHY GPON	0.6 to 9.80 1.25 and 2.5	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering
Custom 10G PHY	9.98 to 12.5	TX FIFOGear boxBit-slip	RX FIFOGear box
PCIe Gen1 (x1, x2 x4, x8) PCIe Gen2 (x1, x2, x4, x8)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding PIPE 2.0 interface to core logic 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer, Byte ordering PIPE 2.0 interface to core logic
PCIe Gen3 (x1, x2, x4, x8)	8.0	 Phase compensation FIFO 128B/130B encoder Scrambler Gear box Bit-slip 	 Block synchronization Rate match FIFO 128B/130B decoder Descrambler Phase compensation FIFO
10GbE	10.3125	TX FIFO64B/66B encoderScramblerGear box	 RX FIFO 64B/66B decoder Descrambler Block synchronization Gear box
Interlaken	3.125 to 12.5	 TX FIFO Frame generator CRC-32 generator Scrambler Disparity generator Gear box 	 RX FIFO Frame generator CRC-32 checker Frame decoder Descrambler Disparity checker Block synchronization Gear box



Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
40GBASE-R Ethernet 100GBASE-R Ethernet	4 x 10.3125 10 x 10.3125	 TX FIFO 64B/66B encoder Scrambler Alignment marker insertion Gearbox Block stripper 	 RX FIFO 64B/66B decoder Descrambler Lane reorder Deskew Alignment marker lock Block synchronization Gear box Destripper
40G and 100G OTN	(4+1) x 11.3 (10+1) x 11.3	 TX FIFO Channel bonding Byte serializer	RX FIFOLane deskewByte deserializer
GbE	1.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding GbE state machine 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering GbE state machine
XAUI	3.125 to 4.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding XAUI state machine for bonding four channels 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering XAUI state machine for realigning four channels
SRIO	1.25 to 6.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding SRIO V2.1-compliant x2 and x4 channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering SRIO V2.1-compliant x2 and x4 deskew state machine



SoC with HPS

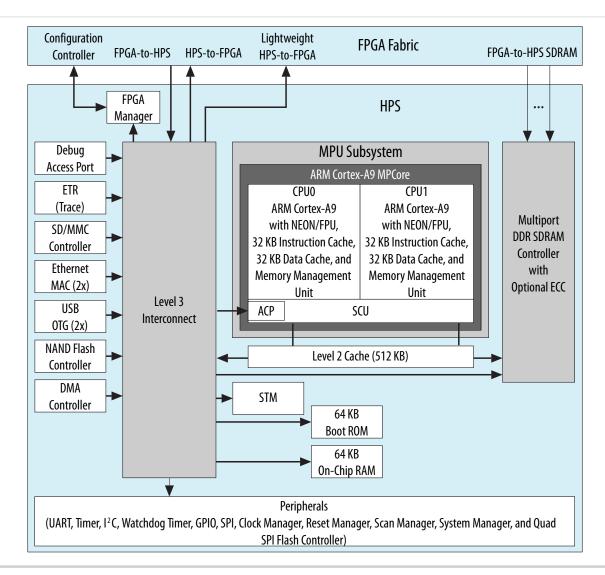
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor





Partial Reconfiguration

Note: Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Altera simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Quartus Prime design software. With the Altera solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Table 23: Configuration Modes and Features of Arria V Devices

Arria V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V⁽¹⁹⁾ programming voltages and several configuration modes.

Mode	Data Width	Max Clock Rate (MHz)	Max Datal Rate (Mbps)	Decompression		Partial econfiguratio (20)	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_



⁽¹⁹⁾ Arria V GZ does not support 3.3 V.

⁽²⁰⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Document Revision History

Date	Version	Changes
December 2015	2015.12.21	 Updated RoHS and optional suffix information in sample ordering code and available options diagrams for Arria V GX and GT devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
January 2015	2015.01.23	 Updated package dimension for Arria V GZ H780 package from 29 mm to 33 mm. Updated dual-core ARM Cortex-A9 MPCore processor maximum frequency from 800 MHz to 1.05 GHz.
December 2013	2013.12.26	 10-Gbps Ethernet (10GbE) PCS and Interlaken PCS are for Arria V GZ only. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Added link to Altera Product Selector for each device variant. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F896 package from 170 to 250. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1152 package from 350 to 385. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1517 package from 528 to 540. Corrected LVDS Transmitter for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 devices from 121 to 120. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Added x2 for PCIe Gen3, Gen 2, and Gen 1.
August 2013	2013.08.19	 Removed the note about the PCIe hard IP on the right side of the device in the F896 package of the Arria V GX variant. These devices do not have PCIe hard IP on the right side. Added transceiver speed grade 6 to the available options of the Arria V SX variant. Corrected the maximum LVDS transmitter channel counts for the Arria V GX A1 and A3 devices from 68 to 67. Corrected the maximum FPGA GPIO count for Arria V ST D5 devices from 540 to 528.



Date	Version	Changes
July 2012	2.1	 Added –I3 speed grade to Figure 1 for Arria V GX devices. Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 12, Table 15, and Table 16. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.3	 Updated Table 1–7 and Table 1–8. Updated Figure 1–9 and Figure 1–10. Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. Added "SoC FPGA with HPS" section. Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. Updated Figure 1–5. Added Figure 1–6. Minor text edits.
August 2011	1.0	Initial release.

